International
IOR Rectifier

PROVISIONAL

SMPS MOSFET

PD - 97002

IRFB52N15DPbF
IRFS52N15DPbF
IRFSL52N15DPbF

HEXFET® Power MOSFET

Applications
- High frequency DC-DC converters
- Plasma Display Panel
- Lead-Free

Benefits
- Low Gate-to-Drain Charge to Reduce Switching Losses
- Fully Characterized Capacitance Including Effective C_{OSS} to Simplify Design, (See App. Note AN1001)
- Fully Characterized Avalanche Voltage and Current

Key Parameters		
V_{DS}	150	V
$V_{DS\ (Avalanche)}$ min.	200	V
$R_{DS(ON)}$ max @ 10V	32	mΩ
T_J max	175	°C

TO-220AB IRFB52N15DPbF | D²Pak IRFS52N15DPbF | TO-262 IRFSL52N15DPbF

Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V ⑦	51*	A
I_D @ T_C = 100°C	Continuous Drain Current, V_{GS} @ 10V ⑦	36*	
I_{DM}	Pulsed Drain Current ①	240	
P_D @T_A = 25°C	Power Dissipation ⑦	3.8	W
P_D @T_C = 25°C	Power Dissipation ⑦	230*	
	Linear Derating Factor ⑦	1.5*	W/°C
V_{GS}	Gate-to-Source Voltage	± 30	V
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torqe, 6-32 or M3 screw⑥	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	–––	0.47*	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface ⑥	0.50	–––	
$R_{\theta JA}$	Junction-to-Ambient⑥	–––	62	
$R_{\theta JA}$	Junction-to-Ambient⑦	–––	40	

* $R_{\theta JC}$ (end of life) for D²Pak and TO-262 = 0.65°C/W. This is the maximum measured value after 1000 temperature cycles from -55 to 150°C and is accounted for by the physical wearout of the die attach medium.

Notes ① through ⑦ are on page 11

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	150	—	—	V	V_{GS} = 0V, I_D = 250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.16	—	V/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	32	mΩ	V_{GS} = 10V, I_D = 36A ④
$V_{GS(th)}$	Gate Threshold Voltage	3.0	—	5.0	V	V_{DS} = V_{GS}, I_D = 250µA
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	µA	V_{DS} = 150V, V_{GS} = 0V
		—	—	250		V_{DS} = 120V, V_{GS} = 0V, T_J = 150°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V_{GS} = 30V
	Gate-to-Source Reverse Leakage	—	—	-100		V_{GS} = -30V

Dynamic @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	19	—	—	S	V_{DS} = 50V, I_D = 36A
Q_g	Total Gate Charge	—	60	89	nC	I_D = 36A
Q_{gs}	Gate-to-Source Charge	—	18	27		V_{DS} = 75V
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	28	42		V_{GS} = 10V, ④
$t_{d(on)}$	Turn-On Delay Time	—	16	—	ns	V_{DD} = 75V
t_r	Rise Time	—	47	—		I_D = 36A
$t_{d(off)}$	Turn-Off Delay Time	—	28	—		R_G = 2.5Ω
t_f	Fall Time	—	25	—		V_{GS} = 10V ④
C_{iss}	Input Capacitance	—	2770	—	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	—	590	—		V_{DS} = 25V
C_{rss}	Reverse Transfer Capacitance	—	110	—		f = 1.0MHz
C_{oss}	Output Capacitance	—	3940	—		V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz
C_{oss}	Output Capacitance	—	260	—		V_{GS} = 0V, V_{DS} = 120V, f = 1.0MHz
C_{oss} eff.	Effective Output Capacitance	—	550	—		V_{GS} = 0V, V_{DS} = 0V to 120V ⑤

Avalanche Characteristics

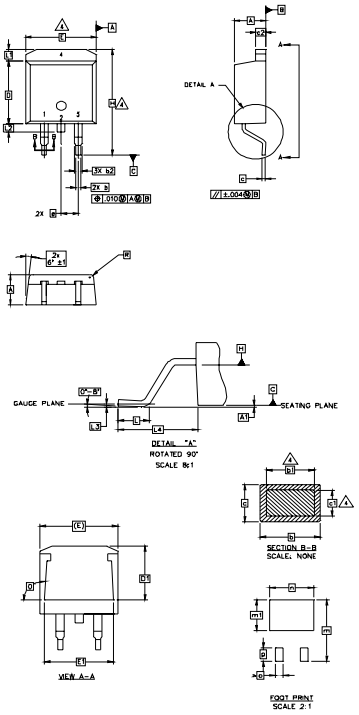
	Parameter	Min.	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②⑥	—	—	470	mJ
I_{AR}	Avalanche Current ①	—	—	36	A
E_{AR}	Repetitive Avalanche Energy ①	—	450	—	mJ
$V_{DS\ (Avalanche)}$	Repetitive Avalanche Voltage ①	200	—	—	V

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	60	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①⑥	—	—	240		
V_{SD}	Diode Forward Voltage	—	—	1.5	V	T_J = 25°C, I_S = 36A, V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	—	140	210	nS	T_J = 25°C, I_F = 36A
Q_{rr}	Reverse RecoveryCharge	—	780	1170	nC	di/dt = 100A/µs ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

D²Pak Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.78	.045	.070	
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	4
c2	1.14	1.65	.045	.065	
D	8.51	9.65	.335	.380	3
D1	6.86		.270		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1		1.65		.065	
L2	1.27	1.78	.050	.070	
L3	0.25 BSC		.010 BSC		
L4	4.78	5.28	.188	.208	
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
o	2.08		.082		
p	3.81		.150		
R	0.51	0.71	.020	.028	
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

HEXFET

1.– GATE
2, 4.– DRAIN
3.– SOURCE

IGBTs, CoPACK

1.– GATE
2, 4.– COLLECTOR
3.– EMITTER

DIODES

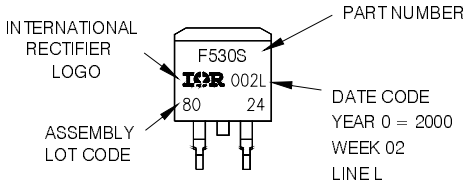
1.– ANODE *
2, 4.– CATHODE
3.– ANODE

* PART DEPENDENT.

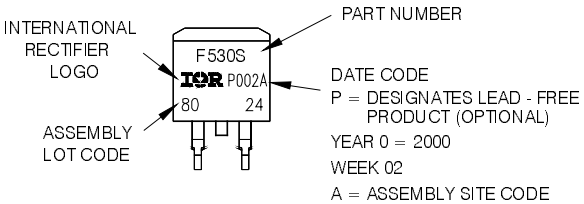
D²Pak Part Marking Information

EXAMPLE: THIS IS AN IRF530S WITH
LOT CODE 8024
ASSEMBLED ON WW 02, 2000
IN THE ASSEMBLY LINE 'L'

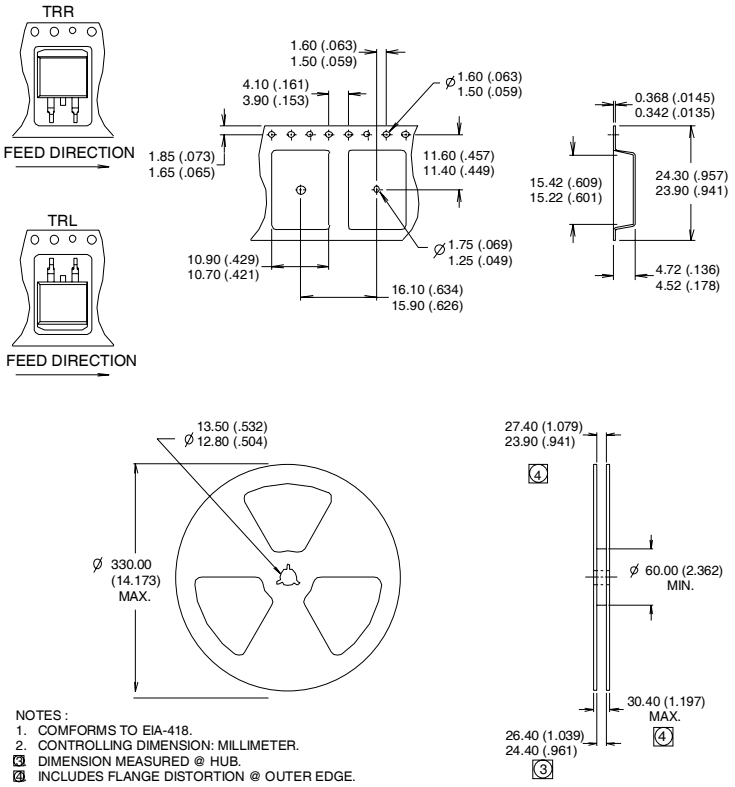
Note: "P" in assembly line position
indicates "Lead – Free"



OR



D²Pak Tape & Reel Information



Notes:

① 1% Duty cycle, 100 pulses, limited by max. junction temperature.

② Starting T_J = 25°C, L = 0.72mH
R_G = 25Ω, I_{AS} = 36A.

③ $I_{SD} \leq$ 36A, di/dt ≤ 400A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq$ 175°C.

④ Pulse width ≤ 300µs; duty cycle ≤ 2%.

⑤ C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

⑥ This is only applied to TO-220AB package.

⑦ This is applied to D²Pak, when mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.

TO-220 package is not recommended for Surface Mount Application.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Automotive [Q101] (IRFB52N15DPbF), & Industrial (IRFS52N15DPbF/IRFSL52N15DPbF) market.

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